

TN60H04BNTE

N-Channel Enhancement Mode Power MOSFET

TO-252

Product Summary

- $V_{DS} = 600V, I_D = 4A$
- $R_{DS(on)} < 2.3\Omega @ V_{GS} = 10V$

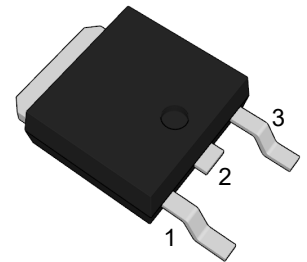
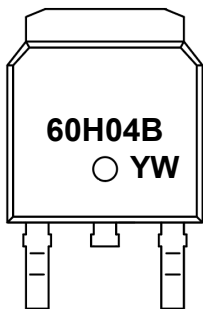
Features

- Advanced Planar Technology
- 100% Avalanche Tested
- RoHS Compliant
- Halogen and Antimony Free
- Moisture Sensitivity Level 3

Application

- AC-DC Switching Power Supplies
- DC-DC Power Converter
- High Voltage High-Bridge PWM Motor Driver

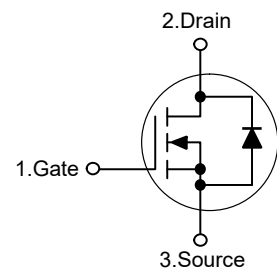
Marking Code



(Top View)

Pin	Description
1	Gate
2	Drain
3	Source

Schematic Diagram



Absolute Maximum Ratings

Ratings at 25°C case temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current-Continuous	I_D	4	A
Drain Current-Pulsed ^{Note1}	I_{DM}	16	A
Maximum Power Dissipation	P_D	147	W
Single Pulse Avalanche Energy ^{Note2}	E_{AS}	170	mJ
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Thermal Characteristics

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.85	°C/W
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Electrical Characteristics

(T_J=25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Off characteristics						
BV _{DSS}	Drain to source breakdown voltage	V _{GS} =0V, I _D =250uA	600			V
ΔBV _{DSS} / ΔT _J	Breakdown voltage temperature coefficient	I _D =250uA, referenced to 25°C		0.5		V/°C
I _{DSS}	Drain to source leakage current	V _{DS} =610V, V _{GS} =0V			1	uA
		V _{DS} =488V, T _C =125°C			50	uA
I _{GSS}	Gate to source leakage current, forward	V _{GS} =30V, V _{DS} =0V			100	nA
	Gate to source leakage current, reverse	V _{GS} =-30V, V _{DS} =0V			-100	nA
On characteristics						
V _{GS(TH)}	Gate threshold voltage	V _{DS} =V _{GS} , I _D =250uA	2.5		4.5	V
R _{DS(ON)}	Drain to source on state resistance	V _{GS} =10V, I _D = 2A		2	2.2	Ω
G _{fs}	Forward Transconductance	V _{DS} = 30 V, I _D = 2A		3.3		S
Dynamic characteristics						
C _{iss}	Input capacitance	V _{GS} =0V, V _{DS} =25V, f=1MHz		586		pF
C _{oss}	Output capacitance			71		
C _{rss}	Reverse transfer capacitance			7.6		
t _{d(on)}	Turn on delay time	V _{DS} =300V, I _D =4A, R _G =25Ω (note 4,5)		12		ns
t _r	Rising time			27		
t _{d(off)}	Turn off delay time			33		
t _f	Fall time			25		
Q _g	Total gate charge	V _{DS} =480V, V _{GS} =10V, I _D =4A (note 4,5)		17		nC
Q _{gs}	Gate-source charge			8		
Q _{gd}	Gate-drain charge			5		

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I _S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			4	A
I _{SM}	Pulsed source current				16	A
V _{SD}	Diode forward voltage drop.	I _S =4A, V _{GS} =0V			1.5	V
T _{rr}	Reverse recovery time	I _S =4A, V _{GS} =0V, dI _F /dt=100A/us		366		ns
Q _{rr}	Reverse recovery Charge			1.9		uC

※. Notes

1. Repetitive rating : pulse width limited by junction temperature.
2. L = 21mH, I_{AS} = 4A, V_{DD} = 50V, R_G=25Ω, Starting T_J = 25°C
3. I_{SD} ≤ 4A, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Starting T_J =25°C
4. Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%.
5. Essentially independent of operating temperature.

Typical Characteristic Curves

Fig. 1. On-state characteristics

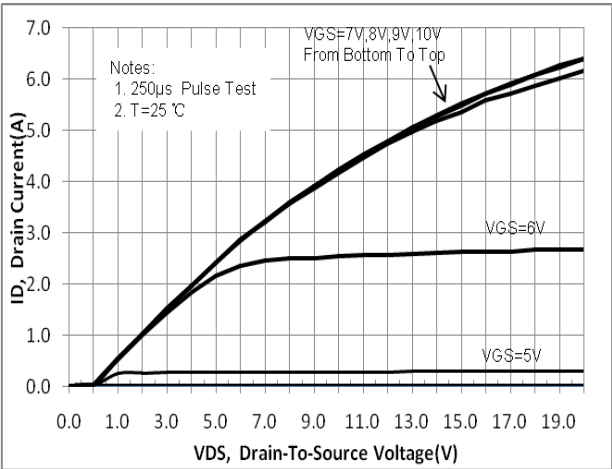


Fig. 2. On-resistance variation vs. drain current and gate voltage

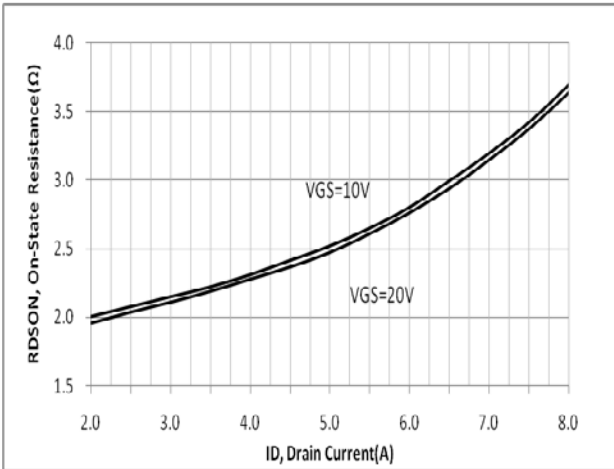


Fig. 3. Gate charge characteristics

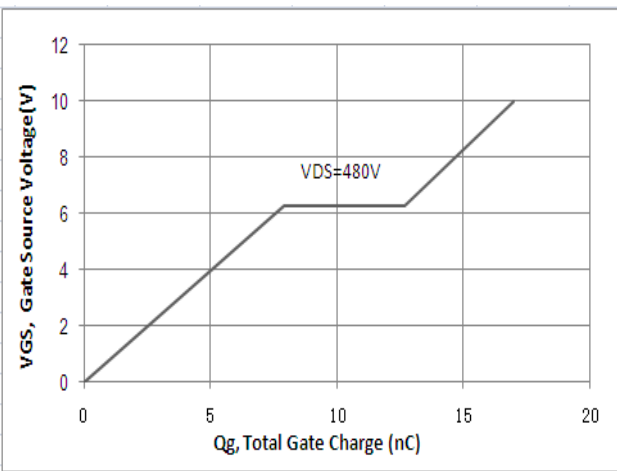


Fig. 4. On state current vs. diode forward voltage

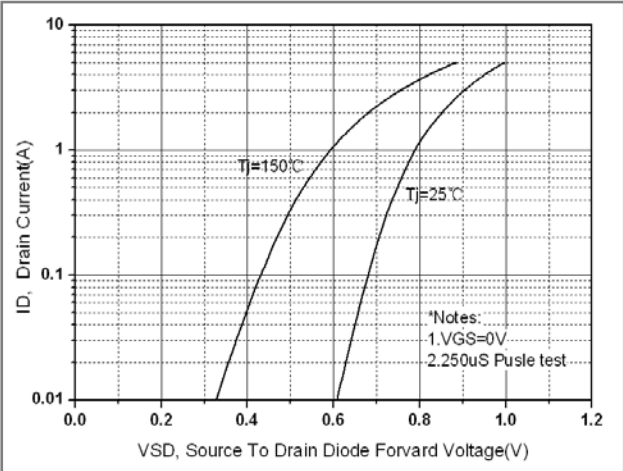


Fig 5. Breakdown Voltage Variation vs. Junction Temperature

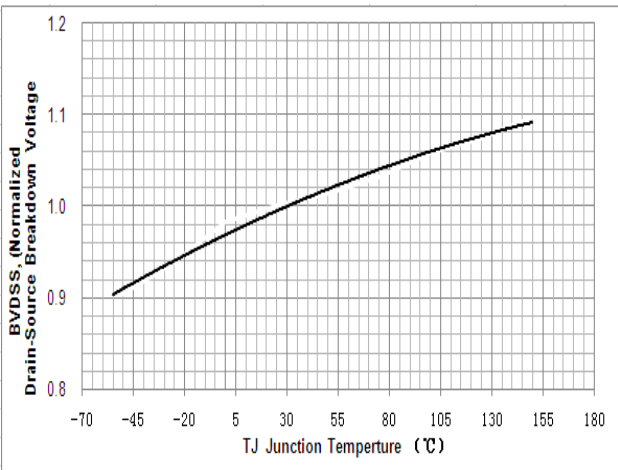


Fig. 6. On resistance variation vs. junction temperature

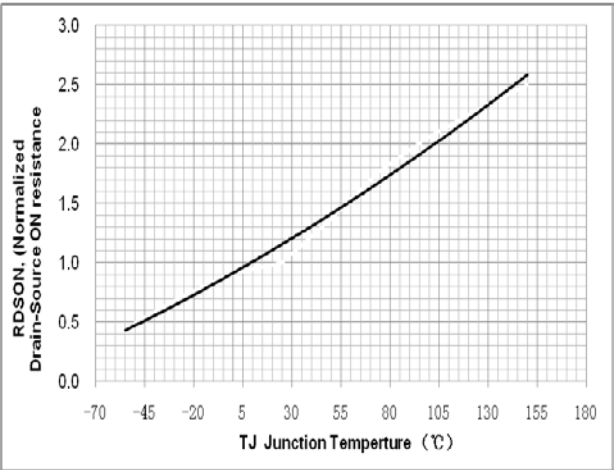


Fig. 7. Maximum safe operating area (TO-251)

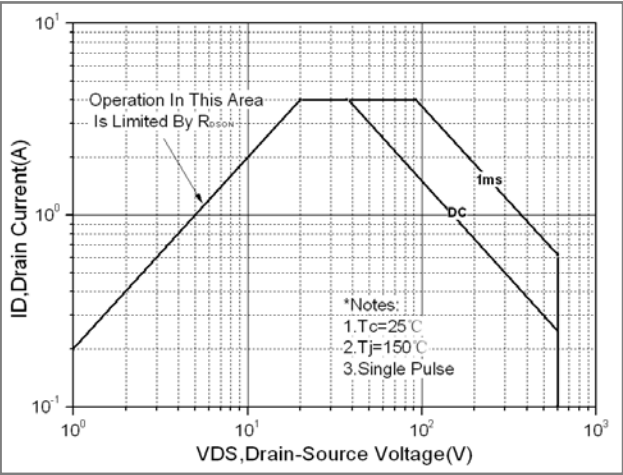


Fig. 8. Transient thermal response curve (TO-251)

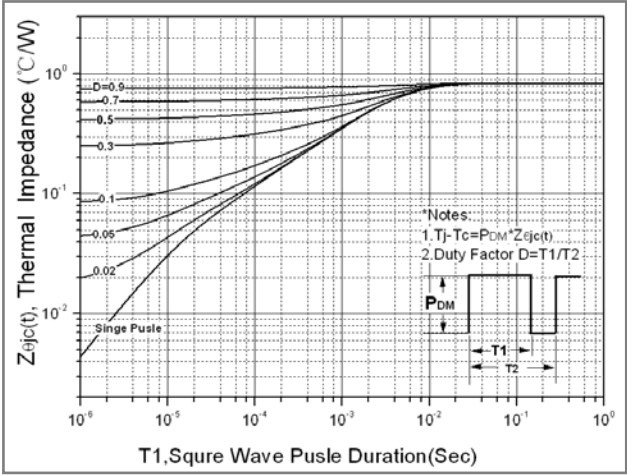


Fig. 9. Maximum safe operating area (TO-252)

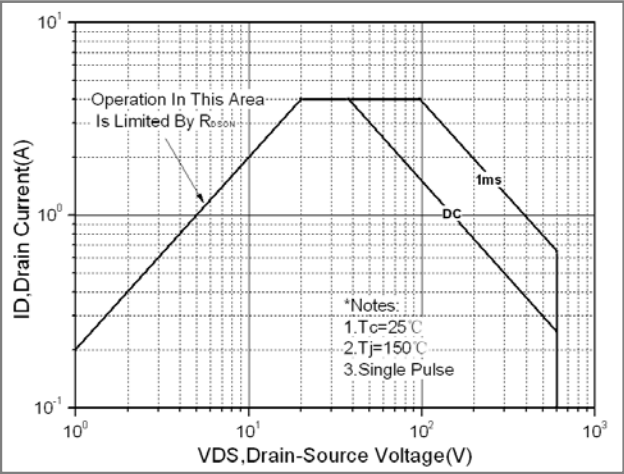


Fig. 10. Transient thermal response curve (TO-252)

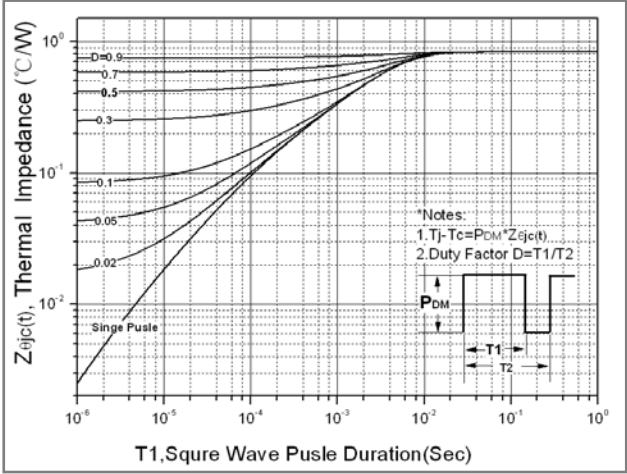
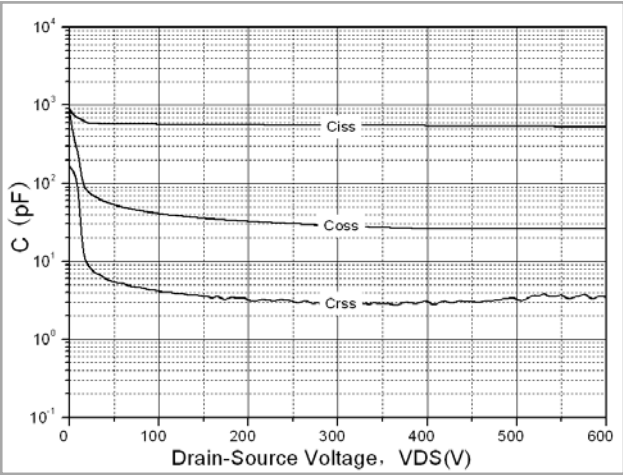


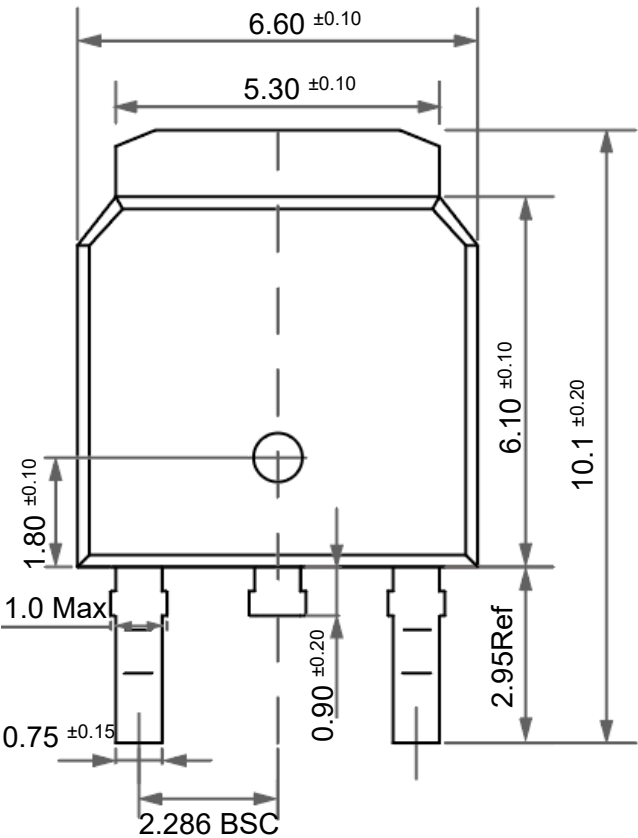
Fig. 11. Capacitance Characteristics



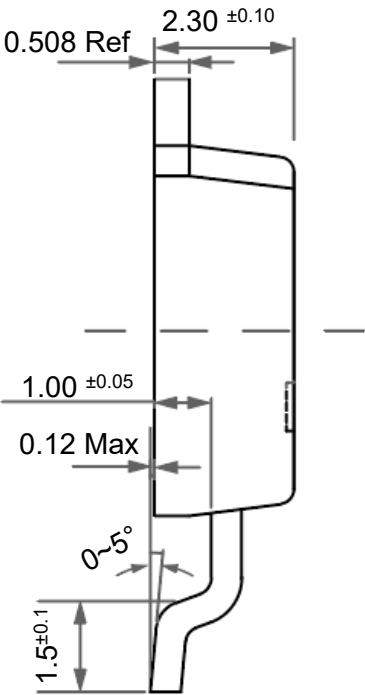
Package Outline

TO-252

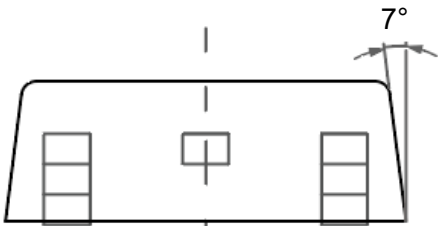
Dimensions in mm



Front View



Side View



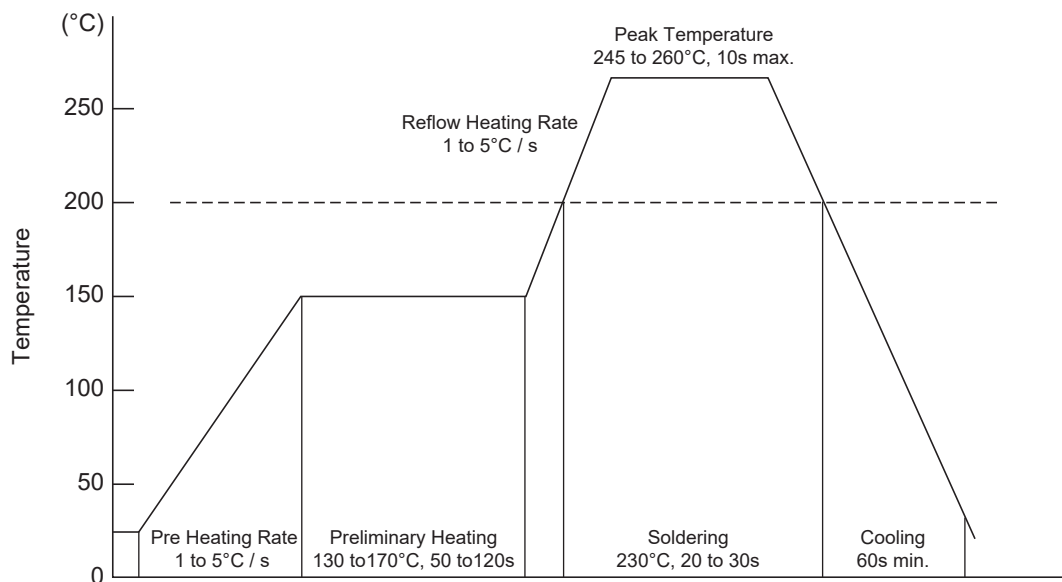
Bottom View

Ordering Information

Device	Package	Shipping
TN60H04BNTE	TO-252	2,500PCS/Reel&13inches

Conditions of Soldering and Storage

◆ Recommended condition of reflow soldering



Recommended peak temperature is over 245°C. If peak temperature is below 245°C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

◆ Conditions of hand soldering

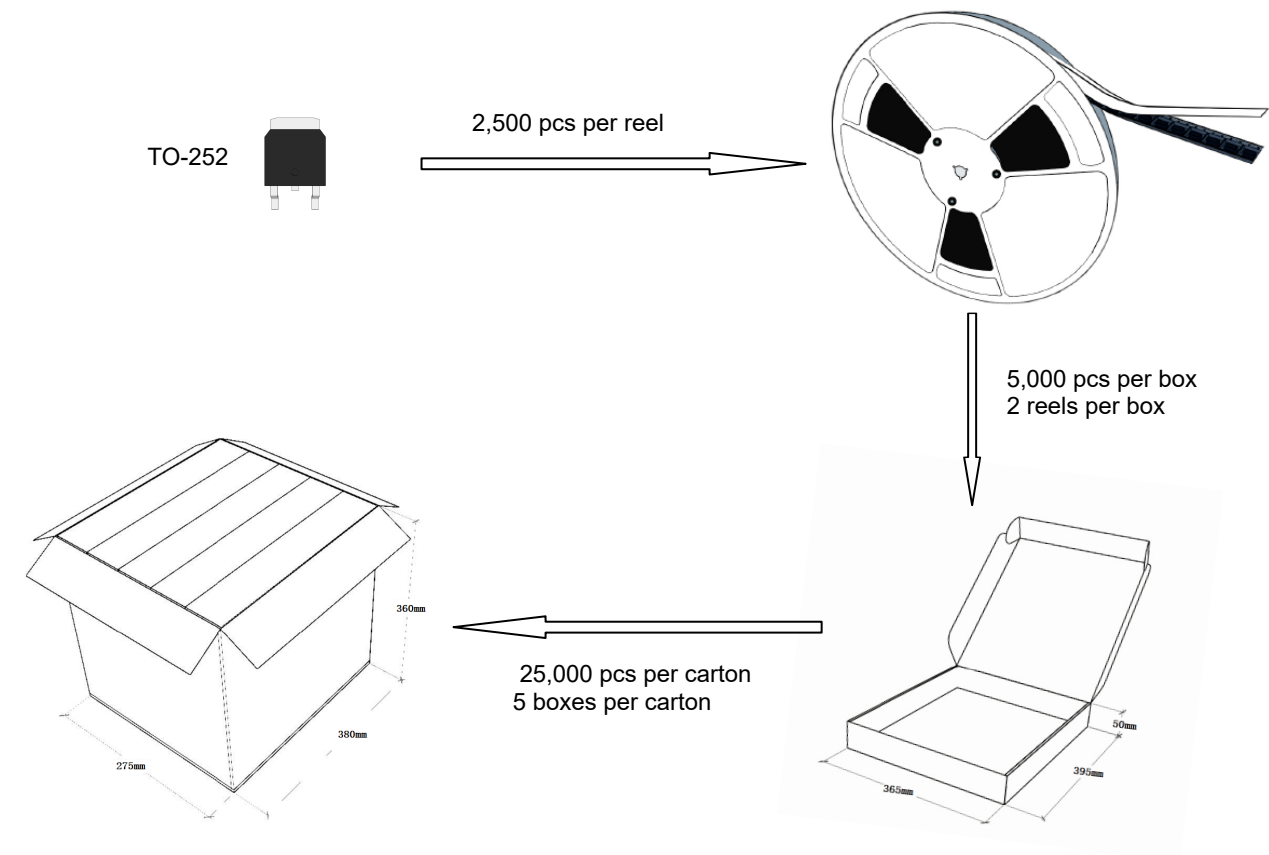
- Temperature: 300°C
- Time: 3s max.
- Times: one time

◆ Storage conditions

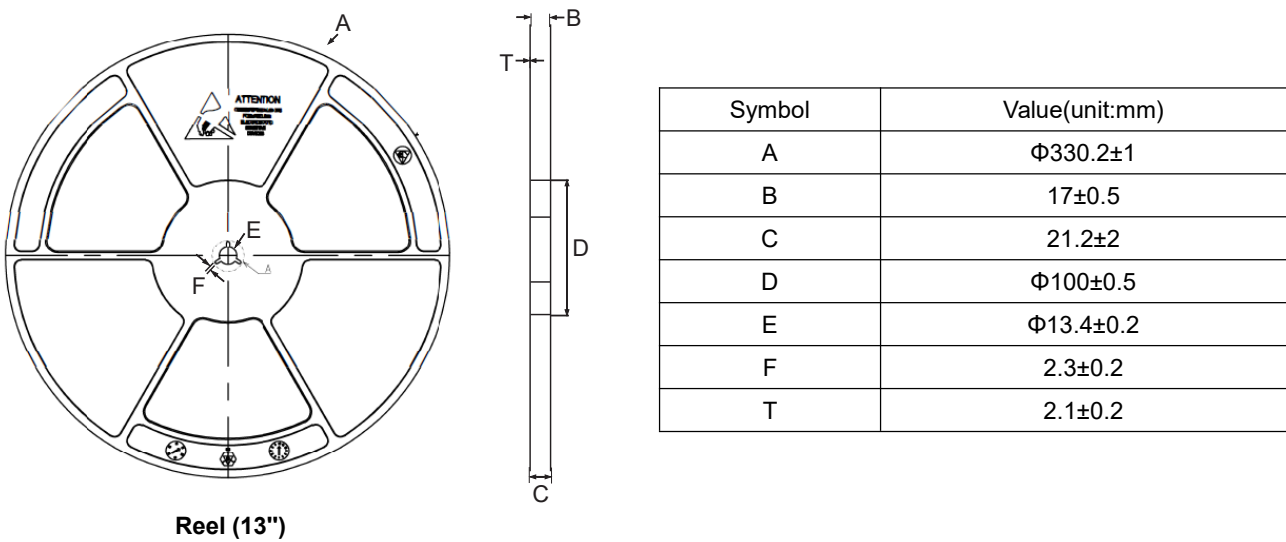
- **Temperature**
5 to 40°C
- **Humidity**
30 to 80% RH
- **Recommended period**
One year after manufacturing

Package Specifications

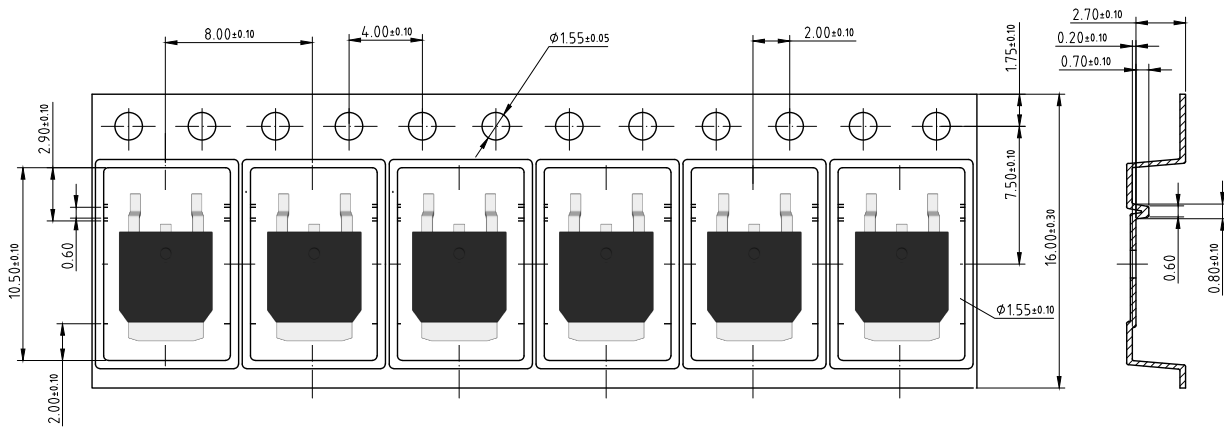
- The method of packaging



reel data




◆ Embossed tape data



Contact Information

TANI website: <http://www.tanisemi.com> Email: tani@tanisemi.com

For additional information, please contact your local Sales Representative.

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